

# SOT1401-3

WLCSP25, wafer level chip-scale package, 25 bumps, 2.555 mm x 2.525 mm x 0.368 mm body (backside coating included)

12 May 2017

Package information

## 1. Package summary

Package type descriptive code	WLCSP25
Package type industry code	WLCSP25
Issue date	12-5-2017
Manufacturer package code	98ASA00848D

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.515	-	2.555	2.595	mm
E	package width	2.485	-	2.525	2.565	mm
A	seated height	0.336	-	0.368	0.4	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	25	-	



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## 2. Package outline

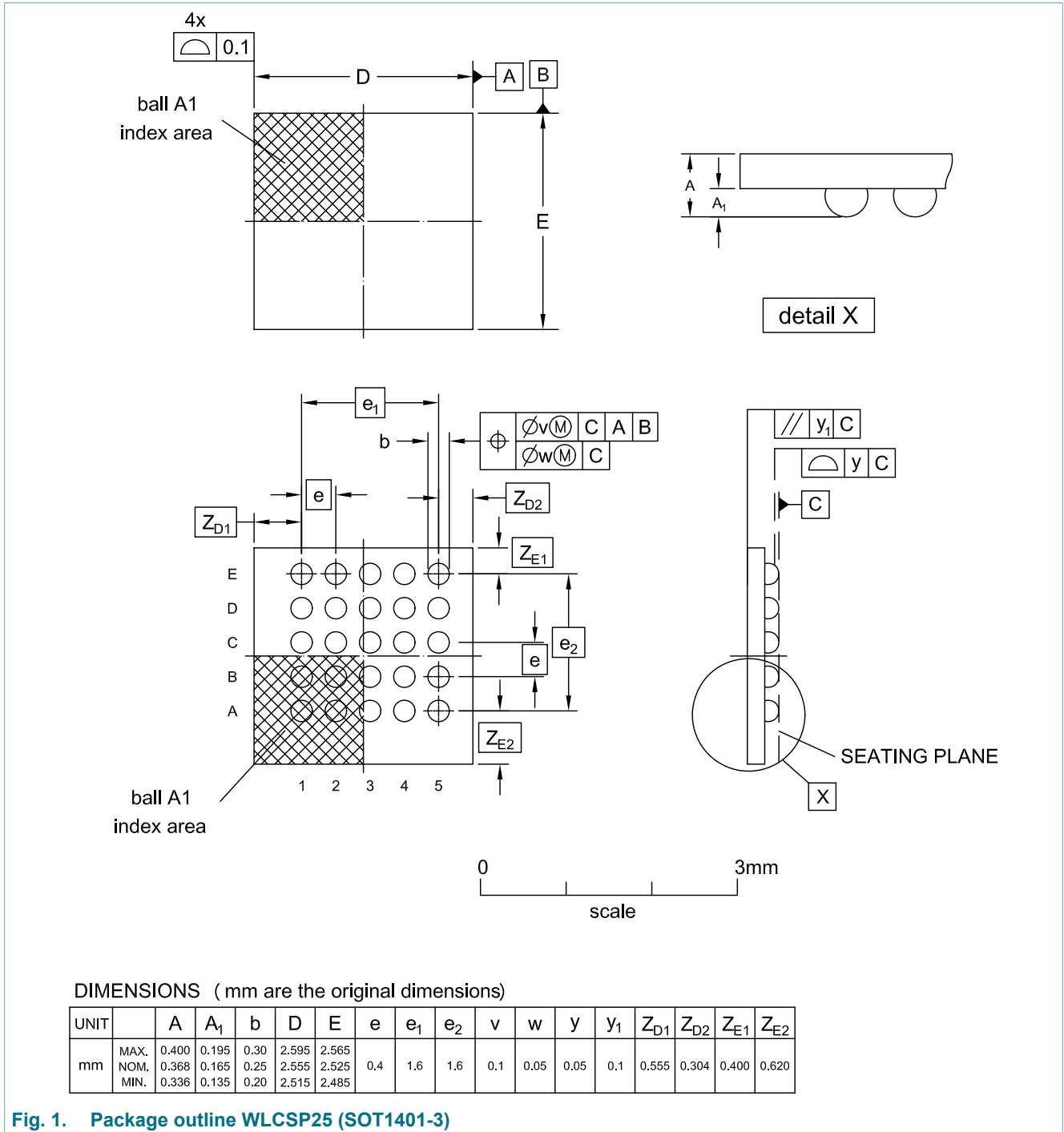


Fig. 1. Package outline WLCSP25 (SOT1401-3)

### 3. Legal information

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## 4. Contents

---

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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